

8A, 200V Ultrafast Dual Diodes

The MUR1620CT and RURP820CC are ultrafast dual diodes with soft recovery characteristics ($t_{rr} < 25\text{ns}$). They have low forward voltage drop and are silicon nitride passivated ionimplanted epitaxial planar construction.

These devices are intended for use as freewheeling/clamping diodes and rectifiers in a variety of switching power supplies and other power switching applications. Their low stored charge and ultrafast soft recovery minimize ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors.

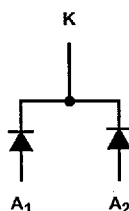
Formerly developmental type TA09224.

Ordering Information

PART NUMBER	PACKAGE	BRAND
MUR1620CT	TO-220AB	MUR1620C
RURP820CC	TO-220AB	RURP820C

NOTE: When ordering, use the entire part number.

Symbol



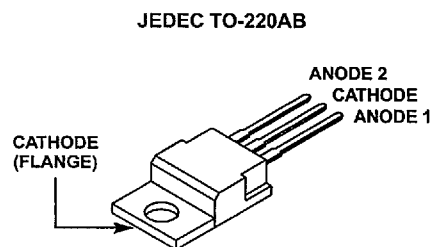
Features

- Ultrafast with Soft Recovery <25ns
- Operating Temperature 175°C
- Reverse Voltage 200V
- Avalanche Energy Rated
- Planar Construction

Applications

- Switching Power Supplies
- Power Switching Circuits
- General Purpose

Packaging



Absolute Maximum Ratings (Per Leg) $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

	MUR1620CT, RURP820CC	UNITS
Peak Repetitive Reverse Voltage	V_{RRM} 200	V
Working Peak Reverse Voltage	V_{RWM} 200	V
DC Blocking Voltage	V_R 200	V
Average Rectified Forward Current	$I_F(AV)$ 8	A
($T_C = 157^\circ\text{C}$)		
Repetitive Peak Surge Current	I_{FRM} 16	A
(Square Wave, 20kHz)		
Nonrepetitive Peak Surge Current	I_{FSM} 100	A
(Halfwave, 1 Phase, 60Hz)		
Maximum Power Dissipation	P_D 50	W
Avalanche Energy (See Figures 10 and 11)	E_{AVL} 20	mJ
Operating and Storage Temperature	T_{STG}, T_J -65 to 175	°C

MUR1620CT, RURP820CC

Electrical Specifications (Per Leg) $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNITS
V_F	$I_F = 8\text{A}$	-	-	0.975	V
	$I_F = 8\text{A}$, $T_C = 150^\circ\text{C}$	-	-	0.895	V
I_R	$V_R = 200\text{V}$	-	-	100	μA
	$V_R = 200\text{V}$, $T_C = 150^\circ\text{C}$	-	-	500	μA
t_{rr}	$I_F = 1\text{A}$, $dI_F/dt = 200\text{A}/\mu\text{s}$	-	-	25	ns
	$I_F = 8\text{A}$, $dI_F/dt = 200\text{A}/\mu\text{s}$	-	-	30	ns
t_a	$I_F = 8\text{A}$, $dI_F/dt = 200\text{A}/\mu\text{s}$	-	13	-	ns
t_b	$I_F = 8\text{A}$, $dI_F/dt = 200\text{A}/\mu\text{s}$	-	5	-	ns
Q_{RR}	$I_F = 8\text{A}$, $dI_F/dt = 200\text{A}/\mu\text{s}$	-	25	-	nC
C_J	$V_R = 10\text{V}$, $I_F = 0\text{A}$	-	60	-	pF
$R_{\theta JC}$		-	-	3	$^\circ\text{C}/\text{W}$

DEFINITIONS

V_F = Instantaneous forward voltage ($p_w = 300\mu\text{s}$, $D = 2\%$).

I_R = Instantaneous reverse current.

t_{rr} = Reverse recovery time (See Figure 9), summation of $t_a + t_b$.

t_a = Time to reach peak reverse current (See Figure 9).

t_b = Time from peak I_{RM} to projected zero crossing of I_{RM} based on a straight line from peak I_{RM} through 25% of I_{RM} (See Figure 9).

Q_{RR} = Reverse recovery charge.

C_J = Junction Capacitance.

$R_{\theta JC}$ = Thermal resistance junction to case.

p_w = Pulse width.

D = Duty cycle.

Typical Performance Curves

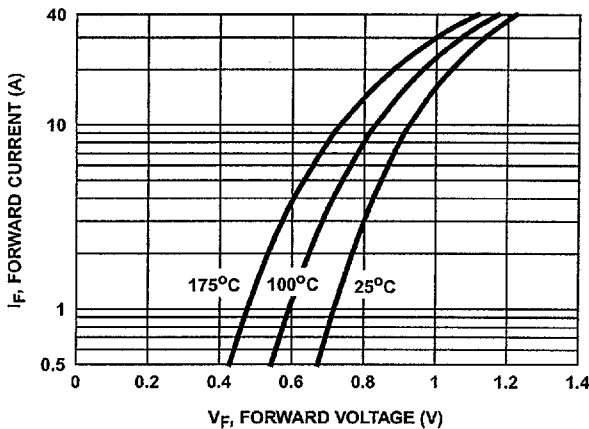


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

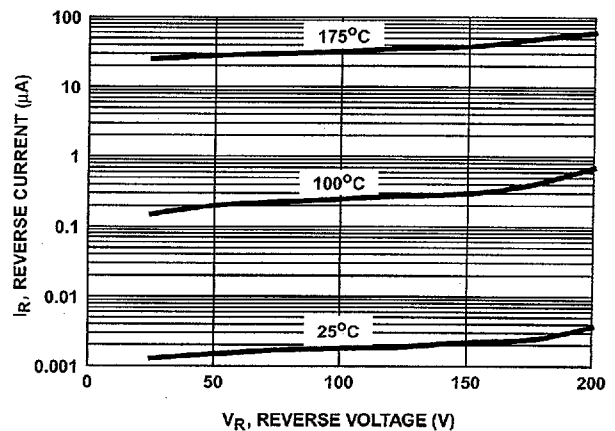


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

Typical Performance Curves (Continued)

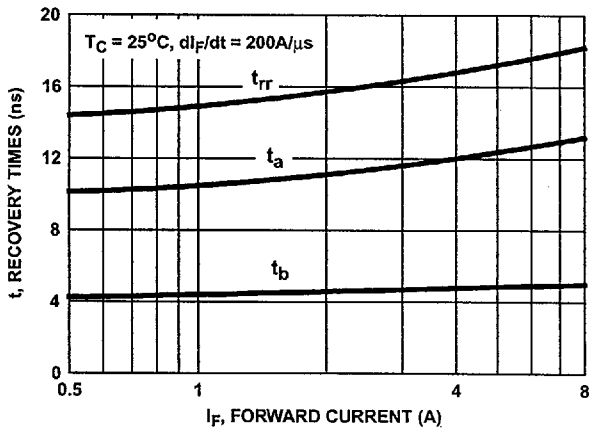


FIGURE 3. t_{rr} , t_a AND t_b CURVES vs FORWARD CURRENT

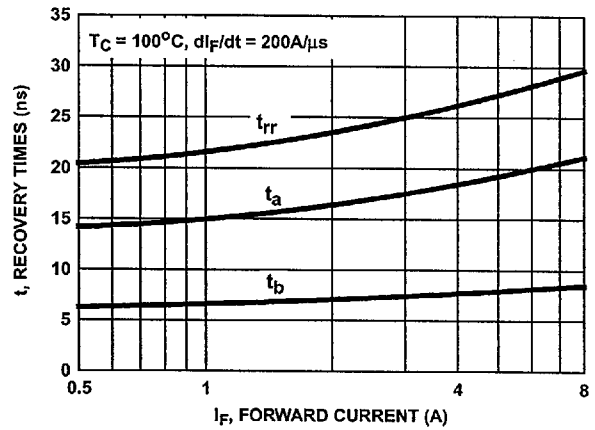


FIGURE 4. t_{rr} , t_a AND t_b CURVES vs FORWARD CURRENT

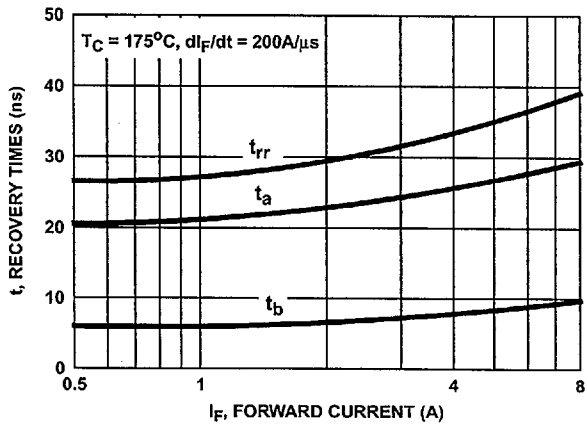


FIGURE 5. t_{rr} , t_a AND t_b CURVES vs FORWARD CURRENT

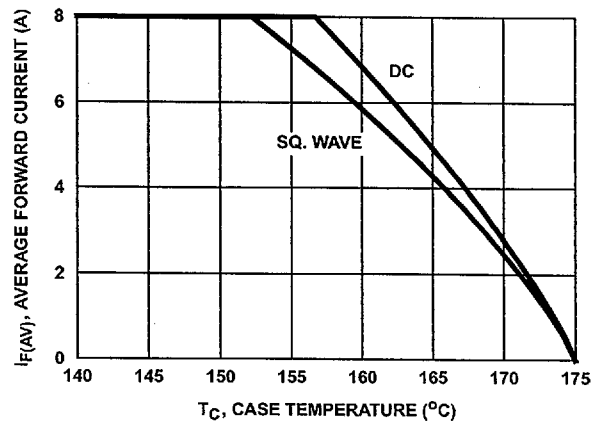


FIGURE 6. CURRENT DERATING CURVE

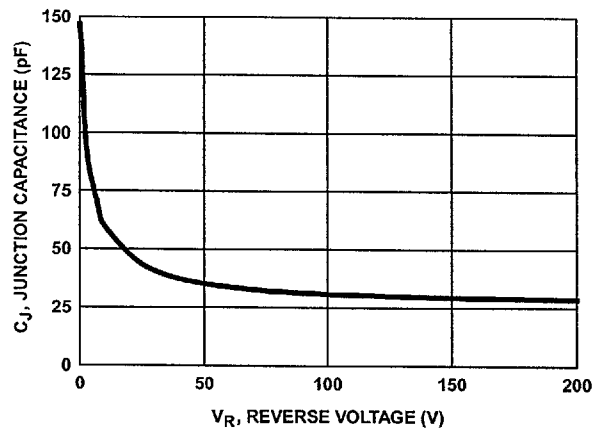


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

Test Circuits and Waveforms

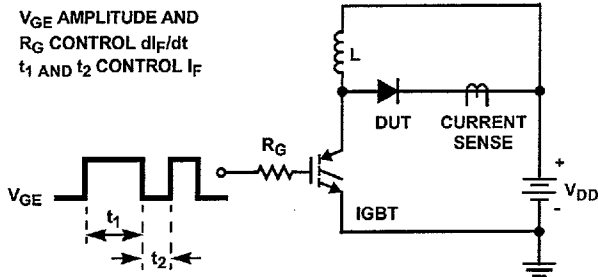


FIGURE 8. t_{rr} TEST CIRCUIT

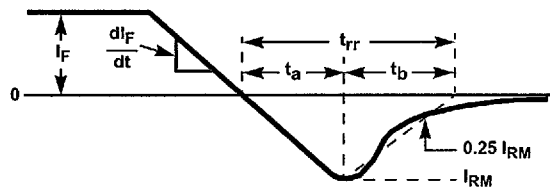


FIGURE 9. t_{rr} WAVEFORMS AND DEFINITIONS

$I = 1A$
 $L = 40mH$
 $R < 0.1\Omega$
 $E_{AVL} = 1/2LI^2 [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]$
 $Q_1 = IGBT (BV_{CES} > DUT V_{R(AVL)})$

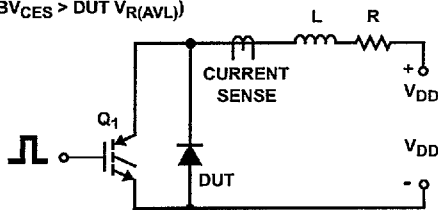


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

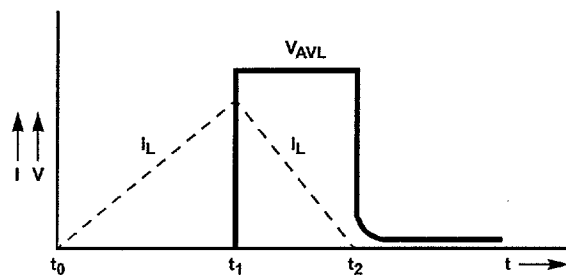


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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